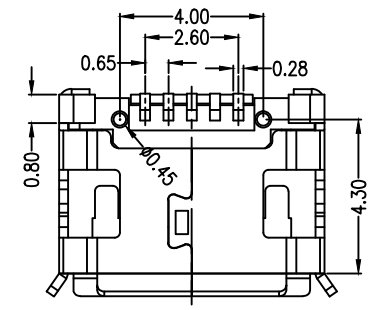
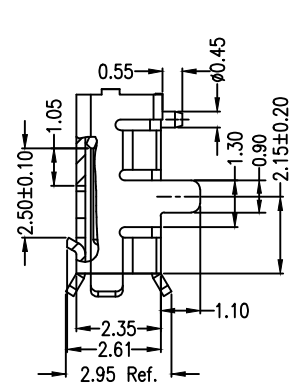
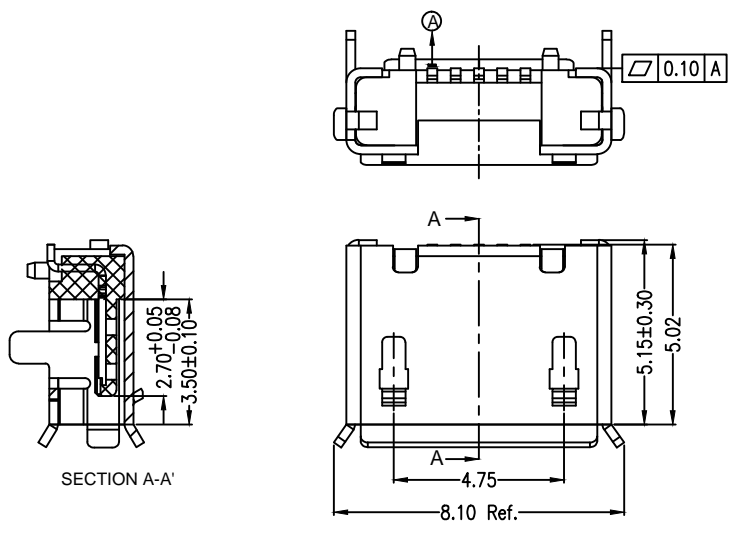
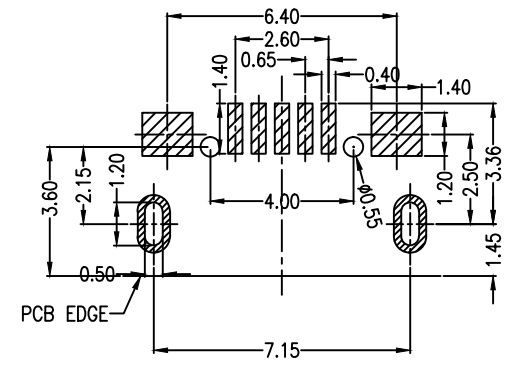
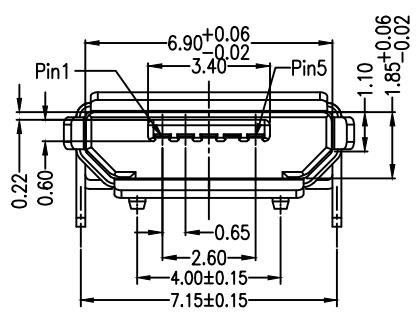


MAPX	MODIFICATION	DATE



- Note:
- Material:
 - Housing: High temperature thermoplastic with g.f,UL94v-0
 - Contact: copper alloy,t=0.20mm, contact area Au 15u" gold-plating, solder area Gold Flash. NICKEL UNDERPLATING OVER ALL 30U"
 - Shell: copper or sus304,t=0.25mm 50u" MIN. TIN(MATTE) PLATING.
 - Specification:
 - Current rating:1.5PIN 1.2A Max/2,3,4PIN 1A Max.
 - Dielectric withstanding voltage: 100 V(ac) for 1 min.
 - Contact resistance: 50 mΩ Max.
 - Insulation resistance: 100 MΩ Min.
 - Total mating force: 3.57 Kgf Max.
 - Total unmating force: 1.0 Kgf Min.
 - Temperature range: -30°C~80°C



RECOMMENDED PCB LAYOUT
PCB图仅供参考

产品图 PRODUCT CHART DWG		深圳市精拓金电子有限公司								
公差一览表 TOLERANCE UNLESS OTHERWISE		单位 UNITS	MM	制图 DRAWING	YANG	制图料号 PRODUCT PART NO.	920-A52A2021S10105			
.X	±0.30	.X	±5.°	比例 SCALE	审核 CHKD	产品名称 PRODUCT NO.	MICRO/5P-F 两脚DIP7.2有边脚长			
.XX	±0.25	.XX	±2.°				1.1有柱加焊脚短端SMT			
.XX	±0.20	.XX	±1.°	日期 DATE	2019.11.23	核准 APPD	黄国荣	角法 VIEW	版本 VER	AO
.XXX	±0.10	.XXX	±0.5°							